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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	60MHz
Connectivity	I²C, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	47
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc2131fbd64-01-15

3.1 Ordering options

Table 2. Ordering options

Type number	Flash memory	RAM	ADC	DAC	Enhanced UARTs, ADC, Fast I/Os, and BOD	Temperature range
LPC2131FBD64/01	32 kB	8 kB	1	-	yes	−40 °C to +85 °C
LPC2132FBD64/01	64 kB	16 kB	1	1	yes	−40 °C to +85 °C
LPC2132FHN64/01	64 kB	16 kB	1	1	yes	−40 °C to +85 °C
LPC2134FBD64/01	128 kB	16 kB	2	1	yes	−40 °C to +85 °C
LPC2136FBD64/01	256 kB	32 kB	2	1	yes	−40 °C to +85 °C
LPC2138FBD64/01	512 kB	32 kB	2	1	yes	−40 °C to +85 °C
LPC2138FHN64/01	512 kB	32 kB	2	1	yes	−40 °C to +85 °C

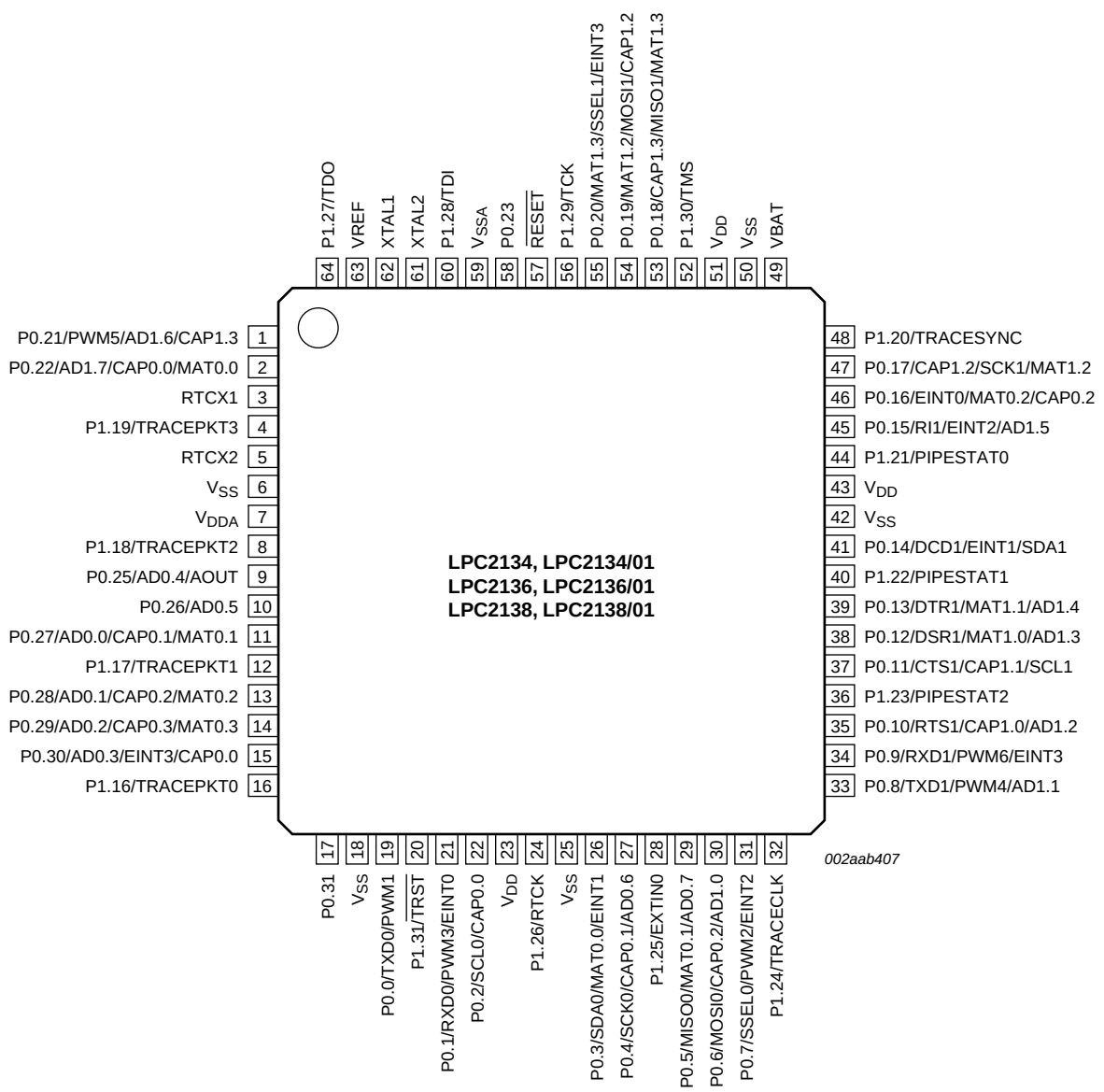
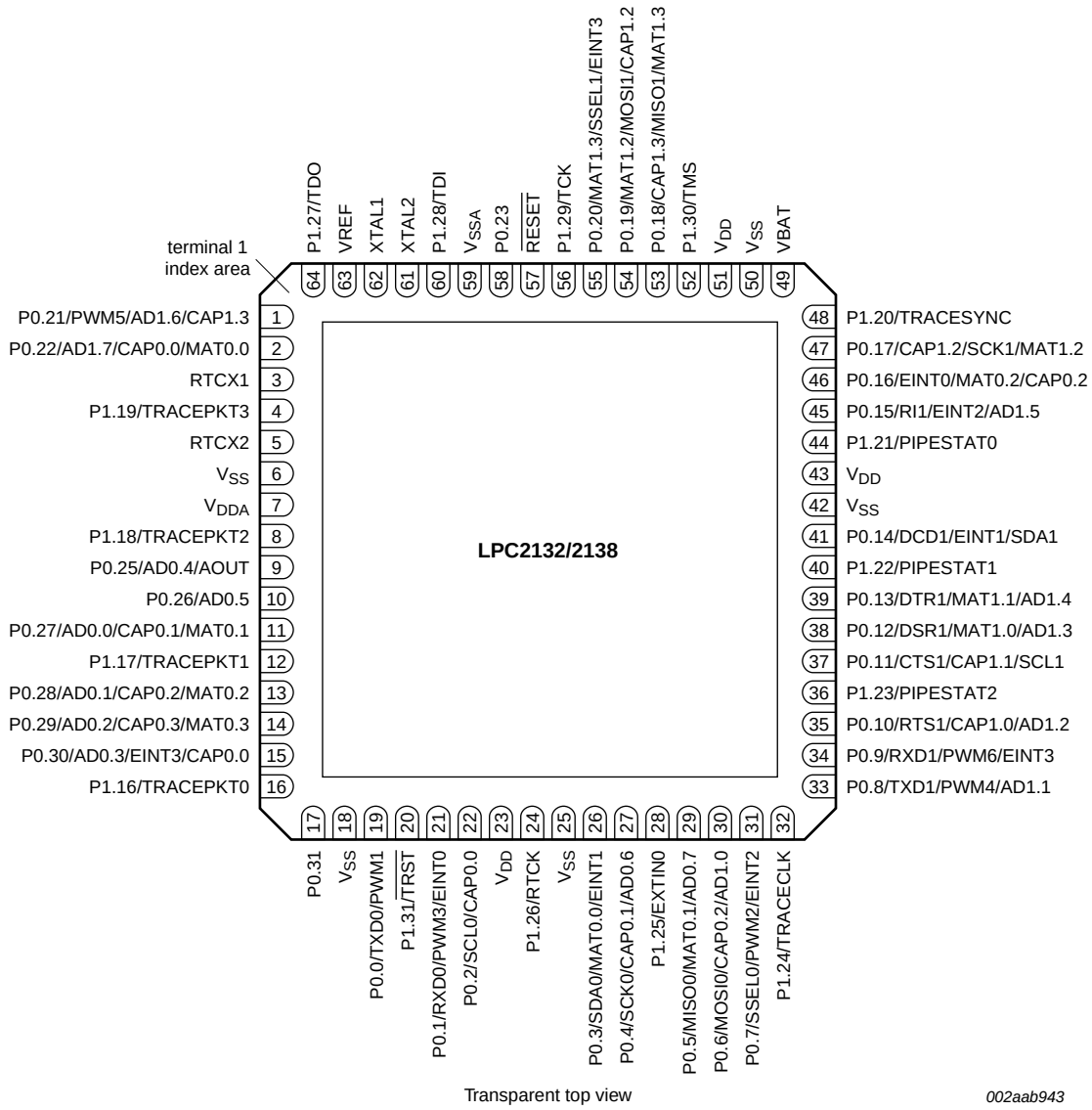


Fig 4. LPC2134/36/38 LQFP64 pin configuration



AD1.7 to AD1.0 only available on LPC2134/36/38.

Fig 5. LPC2132/38 HVQFN64 pin configuration

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
P0.23	58[1]	I/O	General purpose digital input/output pin.
P0.25/AD0.4/ AOUT	9[5]	I	**AD0.4 —** ADC 0, input 4. This analog input is always connected to its pin.
		O	**AOUT —** DAC output. Not available in LPC2131.
P0.26/AD0.5	10[4]	I	**AD0.5 —** ADC 0, input 5. This analog input is always connected to its pin.
P0.27/AD0.0/ CAP0.1/MAT0.1	11[4]	I	**AD0.0 —** ADC 0, input 0. This analog input is always connected to its pin.
		I	**CAP0.1 —** Capture input for Timer 0, channel 1.
		O	**MAT0.1 —** Match output for Timer 0, channel 1.
P0.28/AD0.1/ CAP0.2/MAT0.2	13[4]	I	**AD0.1 —** ADC 0, input 1. This analog input is always connected to its pin.
		I	**CAP0.2 —** Capture input for Timer 0, channel 2.
		O	**MAT0.2 —** Match output for Timer 0, channel 2.
P0.29/AD0.2/ CAP0.3/MAT0.3	14[4]	I	**AD0.2 —** ADC 0, input 2. This analog input is always connected to its pin.
		I	**CAP0.3 —** Capture input for Timer 0, channel 3.
		O	**MAT0.3 —** Match output for Timer 0, channel 3.
P0.30/AD0.3/ EINT3/CAP0.0	15[4]	I	**AD0.3 —** ADC 0, input 3. This analog input is always connected to its pin.
		I	**EINT3 —** External interrupt 3 input.
		I	**CAP0.0 —** Capture input for Timer 0, channel 0.
P0.31	17[6]	O	General purpose digital output only pin. **Important:** This pin MUST NOT be externally pulled LOW when $\overline{\text{RESET}}$ pin is LOW or the JTAG port will be disabled.
P1.0 to P1.31		I/O	**Port 1:** Port 1 is a 32-bit bidirectional I/O port with individual direction controls for each bit. The operation of port 1 pins depends upon the pin function selected via the pin connect block. Pins 0 through 15 of port 1 are not available.
P1.16/ TRACEPKT0	16[6]	O	**TRACEPKT0 —** Trace Packet, bit 0. Standard I/O port with internal pull-up.
P1.17/ TRACEPKT1	12[6]	O	**TRACEPKT1 —** Trace Packet, bit 1. Standard I/O port with internal pull-up.
P1.18/ TRACEPKT2	8[6]	O	**TRACEPKT2 —** Trace Packet, bit 2. Standard I/O port with internal pull-up.
P1.19/ TRACEPKT3	4[6]	O	**TRACEPKT3 —** Trace Packet, bit 3. Standard I/O port with internal pull-up.
P1.20/ TRACESYNC	48[6]	O	**TRACESYNC —** Trace Synchronization. Standard I/O port with internal pull-up. LOW on TRACESYNC while $\overline{\text{RESET}}$ is LOW enables pins P1.25:16 to operate as Trace port after reset.
P1.21/ PIPESTAT0	44[6]	O	**PIPESTAT0 —** Pipeline Status, bit 0. Standard I/O port with internal pull-up.
P1.22/ PIPESTAT1	40[6]	O	**PIPESTAT1 —** Pipeline Status, bit 1. Standard I/O port with internal pull-up.
P1.23/ PIPESTAT2	36[6]	O	**PIPESTAT2 —** Pipeline Status, bit 2. Standard I/O port with internal pull-up.
P1.24/ TRACECLK	32[6]	O	**TRACECLK —** Trace Clock. Standard I/O port with internal pull-up.
P1.25/EXTIN0	28[6]	I	**EXTIN0 —** External Trigger Input. Standard I/O with internal pull-up.

6.4 Memory map

The LPC2131/32/34/36/38 memory map incorporates several distinct regions, as shown in Figure 6.

In addition, the CPU interrupt vectors may be re-mapped to allow them to reside in either flash memory (the default) or on-chip static RAM. This is described in Section 6.18 “System control”.

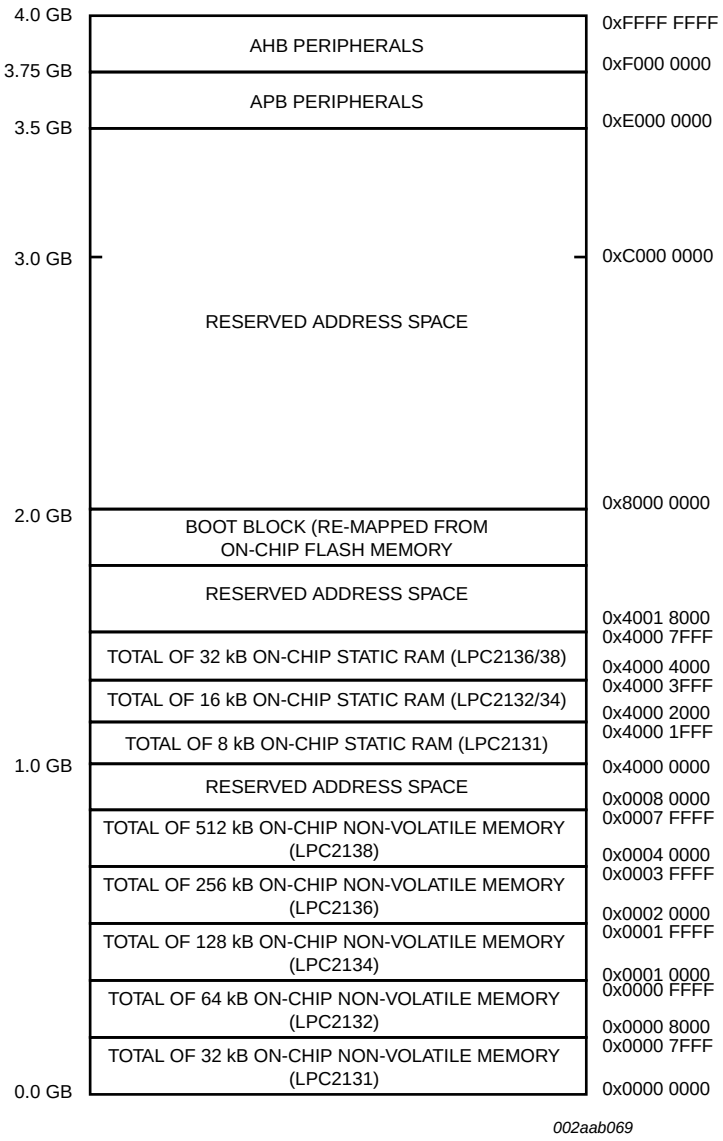


Fig 6. LPC2131/32/34/36/38 memory map

- Built-in baud rate generator.
- Standard modem interface signals included on UART1. (LPC2134/36/38 only)
- The LPC2131/32/34/36/38 transmission FIFO control enables implementation of software (XON/XOFF) flow control on both UARTs and hardware (CTS/RTS) flow control on the LPC2134/36/38 UART1 only.

6.10.2 UART features available in LPC213x/01 only

- Fractional baud rate generator enables standard baud rates such as 115200 to be achieved with any crystal frequency above 2 MHz.
- Auto-bauding.
- Auto-CTS/RTS flow-control fully implemented in hardware (LPC2134/36/38 only).

6.11 I^2C-bus serial I/O controller

The LPC2131/32/34/36/38 each contain two I^2C-bus controllers.

The I^2C-bus is bidirectional, for inter-IC control using only two wires: a Serial Clock Line (SCL), and a Serial DAta line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver or a transmitter with the capability to both receive and send information (such as memory)). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I^2C-bus is a multi-master bus, it can be controlled by more than one bus master connected to it.

This I^2C-bus implementation supports bit rates up to 400 kbit/s (Fast I^2C).

6.11.1 Features

- Standard I^2C compliant bus interface.
- Easy to configure as Master, Slave, or Master/Slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus may be used for test and diagnostic purposes.

6.12 SPI serial I/O controller

The LPC2131/32/34/36/38 each contain one SPI controller. The SPI is a full duplex serial interface, designed to be able to handle multiple masters and slaves connected to a given bus. Only a single master and a single slave can communicate on the interface during a given data transfer. During a data transfer the master always sends a byte of data to the slave, and the slave always sends a byte of data to the master.

- Stop timer on match with optional interrupt generation.
- Reset timer on match with optional interrupt generation.

- Four external outputs per timer/counter corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.

6.15 Watchdog timer

The purpose of the watchdog is to reset the microcontroller within a reasonable amount of time if it enters an erroneous state. When enabled, the watchdog will generate a system reset if the user program fails to 'feed' (or reload) the watchdog within a predetermined amount of time.

6.15.1 Features

- Internally resets chip if not periodically reloaded.
- Debug mode.
- Enabled by software but requires a hardware reset or a watchdog reset/interrupt to be disabled.
- Incorrect/Incomplete feed sequence causes reset/interrupt if enabled.
- Flag to indicate watchdog reset.
- Programmable 32-bit timer with internal pre-scaler.
- Selectable time period from ($T_{cy(PCLK)} \times 256 \times 4$) to ($T_{cy(PCLK)} \times 2^{32} \times 4$) in multiples of $T_{cy(PCLK)} \times 4$.

6.16 Real-time clock

The Real-Time Clock (RTC) is designed to provide a set of counters to measure time when normal or idle operating mode is selected. The RTC has been designed to use little power, making it suitable for battery powered systems where the CPU is not running continuously (Idle mode).

6.16.1 Features

- Measures the passage of time to maintain a calendar and clock.
- Ultra-low power design to support battery powered systems.
- Provides Seconds, Minutes, Hours, Day of Month, Month, Year, Day of Week, and Day of Year.
- Can use either the RTC dedicated 32 kHz oscillator input or clock derived from the external crystal/oscillator input at XTAL1. Programmable Reference Clock Divider allows fine adjustment of the RTC.
- Dedicated power supply pin can be connected to a battery or the main 3.3 V.

6.17 Pulse width modulator

The PWM is based on the standard Timer block and inherits all of its features, although only the PWM function is pinned out on the LPC2131/32/34/36/38. The Timer is designed to count cycles of the peripheral clock (PCLK) and optionally generate interrupts or perform other actions when specified timer values occur, based on seven match registers. The PWM function is also based on match register events.

The ability to separately control rising and falling edge locations allows the PWM to be used for more applications. For instance, multi-phase motor control typically requires three non-overlapping PWM outputs with individual control of all three pulse widths and positions.

Two match registers can be used to provide a single edge controlled PWM output. One match register (MR0) controls the PWM cycle rate, by resetting the count upon match. The other match register controls the PWM edge position. Additional single edge controlled PWM outputs require only one match register each, since the repetition rate is the same for all PWM outputs. Multiple single edge controlled PWM outputs will all have a rising edge at the beginning of each PWM cycle, when an MR0 match occurs.

Three match registers can be used to provide a PWM output with both edges controlled. Again, the MR0 match register controls the PWM cycle rate. The other match registers control the two PWM edge positions. Additional double edge controlled PWM outputs require only two match registers each, since the repetition rate is the same for all PWM outputs.

With double edge controlled PWM outputs, specific match registers control the rising and falling edge of the output. This allows both positive going PWM pulses (when the rising edge occurs prior to the falling edge), and negative going PWM pulses (when the falling edge occurs prior to the rising edge).

6.17.1 Features

- Seven match registers allow up to six single edge controlled or three double edge controlled PWM outputs, or a mix of both types.
- The match registers also allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Supports single edge controlled and/or double edge controlled PWM outputs. Single edge controlled PWM outputs all go HIGH at the beginning of each cycle unless the output is a constant LOW. Double edge controlled PWM outputs can have either edge occur at any position within a cycle. This allows for both positive going and negative going pulses.
- Pulse period and width can be any number of timer counts. This allows complete flexibility in the trade-off between resolution and repetition rate. All PWM outputs will occur at the same repetition rate.
- Double edge controlled PWM outputs can be programmed to be either positive going or negative going pulses.

The wake-up timer monitors the crystal oscillator as the means of checking whether it is safe to begin code execution. When power is applied to the chip, or some event caused the chip to exit Power-down mode, some time is required for the oscillator to produce a signal of sufficient amplitude to drive the clock logic. The amount of time depends on many factors, including the rate of V_{DD} ramp (in the case of power on), the type of crystal and its electrical characteristics (if a quartz crystal is used), as well as any other external circuitry (e.g. capacitors), and the characteristics of the oscillator itself under the existing ambient conditions.

6.18.4 Brownout detector

The LPC2131/32/34/36/38 include 2-stage monitoring of the voltage on the V_{DD} pins. If this voltage falls below 2.9 V, the BOD asserts an interrupt signal to the Vectored Interrupt Controller. This signal can be enabled for interrupt; if not, software can monitor the signal by reading dedicated register.

The second stage of low-voltage detection asserts reset to inactivate the LPC2131/32/34/36/38 when the voltage on the V_{DD} pins falls below 2.6 V. This reset prevents alteration of the flash as operation of the various elements of the chip would otherwise become unreliable due to low voltage. The BOD circuit maintains this reset down below 1 V, at which point the POR circuitry maintains the overall reset.

Both the 2.9 V and 2.6 V thresholds include some hysteresis. In normal operation, this hysteresis allows the 2.9 V detection to reliably interrupt, or a regularly-executed event loop to sense the condition.

Features available only in LPC213x/01 parts include ability to put the BOD in power-down mode, turn it on or off and to control when the BOD will reset the LPC213x/01 microcontroller. This can be used to further reduce power consumption when a low power mode (such as Power Down) is invoked.

6.18.5 Code security

This feature of the LPC2131/32/34/36/38 allow an application to control whether it can be debugged or protected from observation.

If after reset on-chip bootloader detects a valid checksum in flash and reads 0x8765 4321 from address 0x1FC in flash, debugging will be disabled and thus the code in flash will be protected from observation. Once debugging is disabled, it can be enabled only by performing a full chip erase using the ISP.

6.18.6 External interrupt inputs

The LPC2131/32/34/36/38 include up to nine edge or level sensitive External Interrupt Inputs as selectable pin functions. When the pins are combined, external events can be processed as four independent interrupt signals. The External Interrupt Inputs can optionally be used to wake up the processor from Power-down mode.

6.18.7 Memory Mapping Control

The Memory Mapping Control alters the mapping of the interrupt vectors that appear beginning at address 0x0000 0000. Vectors may be mapped to the bottom of the on-chip flash memory, or to the on-chip static RAM. This allows code running in different memory spaces to have control of the interrupts.

The ARM core has a Debug Communication Channel function built-in. The debug communication channel allows a program running on the target to communicate with the host debugger or another separate host without stopping the program flow or even entering the debug state. The debug communication channel is accessed as a co-processor 14 by the program running on the ARM7TDMI-S core. The debug communication channel allows the JTAG port to be used for sending and receiving data without affecting the normal program flow. The debug communication channel data and control registers are mapped in to addresses in the EmbeddedICE logic.

6.19.2 Embedded trace

Since the LPC2131/32/34/36/38 have significant amounts of on-chip memory, it is not possible to determine how the processor core is operating simply by observing the external pins. The Embedded Trace Macrocell provides real-time trace capability for deeply embedded processor cores. It outputs information about processor execution to the trace port.

The ETM is connected directly to the ARM core and not to the main AMBA system bus. It compresses the trace information and exports it through a narrow trace port. An external trace port analyzer must capture the trace information under software debugger control. Instruction trace (or PC trace) shows the flow of execution of the processor and provides a list of all the instructions that were executed. Instruction trace is significantly compressed by only broadcasting branch addresses as well as a set of status signals that indicate the pipeline status on a cycle by cycle basis. Trace information generation can be controlled by selecting the trigger resource. Trigger resources include address comparators, counters and sequencers. Since trace information is compressed the software debugger requires a static image of the code being executed. Self-modifying code can not be traced because of this restriction.

6.19.3 RealMonitor

RealMonitor is a configurable software module, developed by ARM Inc., which enables real time debug. It is a lightweight debug monitor that runs in the background while users debug their foreground application. It communicates with the host using the DCC, which is present in the EmbeddedICE logic. The LPC2131/32/34/36/38 contain a specific configuration of RealMonitor software programmed into the on-chip flash memory.

7. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage (core and external rail)			–0.5	+3.6	V
V_{DDA}	analog 3.3 V pad supply voltage			–0.5	+4.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT	for the RTC		–0.5	+4.6	V
$V_{i(VREF)}$	input voltage on pin VREF			–0.5	+4.6	V
V_{IA}	analog input voltage	on ADC related pins		–0.5	+5.1	V
V_I	input voltage	5 V tolerant I/O pins; only valid when the V_{DD} supply voltage is present	[2]	–0.5	+6.0	V
		other I/O pins	[2][3]	–0.5	V_{DD} + 0.5	V
I_{DD}	supply current	per supply pin	[4]	-	100	mA
I_{SS}	ground current	per ground pin	[4]	-	100	mA
I_{sink}	sink current	for I^2C-bus; DC; T = 85 °C		-	20	mA
T_{stg}	storage temperature		[5]	–40	+125	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{ESD}	electrostatic discharge voltage	human body model	[6]			
		all pins		–4000	+4000	V

[1] The following applies to the Limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] Not to exceed 4.6 V.

[4] The peak current is limited to 25 times the corresponding maximum current.

[5] Dependent on package type.

[6] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

8. Static characteristics

Table 6. Static characteristics

T_{amb} = −40 °C to +85 °C for commercial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
V_{DD}	supply voltage (core and external rail)			3.0	3.3	3.6	V
V_{DDA}	analog 3.3 V pad supply voltage			2.5	3.3	3.6	V
$V_{i(VBAT)}$	input voltage on pin VBAT		[2]	2.0	3.3	3.6	V
$V_{i(VREF)}$	input voltage on pin VREF			2.5	3.3	3.6	V
Standard port pins, $\overline{\text{RESET}}$, P1.26/RTCK							
I_{IL}	LOW-level input current	V_I = 0 V; no pull-up		-	-	3	μA
I_{IH}	HIGH-level input current	$V_I = V_{DD}$; no-pull-down		-	-	3	μA
I_{OZ}	OFF-state output current	V_O = 0 V; $V_O = V_{DD}$; no pull-up/down		-	-	3	μA
I_{latch}	I/O latch-up current	$-(0.5V_{DD}) < V_I < (1.5V_{DD})$; T_j < 125 °C		-	-	100	mA
V_I	input voltage	pin configured to provide a digital function	[3][4][5] [6]	0	-	5.5	V
V_O	output voltage	output active		0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage			2.0	-	-	V
V_{IL}	LOW-level input voltage			-	-	0.8	V
V_{hys}	hysteresis voltage			0.4	-	-	V
V_{OH}	HIGH-level output voltage	I_{OH} = −4 mA	[7]	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	I_{OL} = −4 mA	[7]	-	-	0.4	V
I_{OH}	HIGH-level output current	$V_{OH} = V_{DD}$ − 0.4 V	[7]	−4	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V	[7]	4	-	-	mA
I_{OHS}	HIGH-level short-circuit output current	V_{OH} = 0 V	[8]	-	-	−45	mA
I_{OLS}	LOW-level short-circuit output current	$V_{OL} = V_{DDA}$	[8]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	[9]	10	50	150	μA
I_{pu}	pull-up current	V_I = 0 V	[10]	−15	−50	−85	μA
		$V_{DD} < V_I$ < 5 V	[9]	0	0	0	μA
$I_{DD(act)}$	active mode supply current	V_{DD} = 3.3 V; T_{amb} = 25 °C; code `while(1){}` executed from flash, no active peripherals					
		CCLK = 10 MHz		-	10	-	mA
		CCLK = 60 MHz		-	40	-	mA
$I_{DD(pd)}$	Power-down mode supply current	V_{DD} = 3.3 V; T_{amb} = 25 °C		-	60	-	μA
		V_{DD} = 3.3 V; T_{amb} = 85 °C		-	200	500	μA

Table 6. Static characteristics *…continued*

T_{amb} = −40 °C to +85 °C for commercial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{BATpd}	Power-down mode battery supply current	RTC clock = 32 kHz (from RTCXn pins); T_{amb} = 25 °C					
		V_{DD} = 3.0 V; $V_{i(VBAT)}$ = 2.5 V	[11]	-	14	-	μA
		V_{DD} = 3.0 V; $V_{i(VBAT)}$ = 3.0 V		-	16	-	μA
		V_{DD} = 3.3 V; $V_{i(VBAT)}$ = 3.3 V		-	18	-	μA
		V_{DD} = 3.6 V; $V_{i(VBAT)}$ = 3.6 V		-	20	-	μA
I_{BATact}	active mode battery supply current	CCLK = 60 MHz; PCLK = 15 MHz; PCLK enabled to RTCK; RTC clock = 32 kHz (from RTCXn pins); T_{amb} = 25 °C	[11]				
		V_{DD} = 3.0 V; $V_{i(VBAT)}$ = 3.0 V		-	78	-	μA
		V_{DD} = 3.3 V; $V_{i(VBAT)}$ = 3.3 V		-	80	-	μA
		V_{DD} = 3.6 V; $V_{i(VBAT)}$ = 3.6 V		-	82	-	μA
$I_{BATact(opt)}$	optimized active mode battery supply current	PCLK disabled to RTCK in the PCONP register; RTC clock = 32 kHz (from RTCXn pins); T_{amb} = 25 °C; $V_{i(VBAT)}$ = 3.3 V	[11][12]				
		CCLK = 6 MHz		-	21	-	μA
		CCLK = 25 MHz		-	23	-	μA
		CCLK = 50 MHz		-	27	-	μA
		CCLK = 60 MHz		-	30	-	μA
I^2C-bus pins							
V_{IH}	HIGH-level input voltage			$0.7V_{DD}$	-	-	V
V_{IL}	LOW-level input voltage			-	-	$0.3V_{DD}$	V
V_{hys}	hysteresis voltage			-	$0.05V_{DD}$	-	V
V_{OL}	LOW-level output voltage	I_{OLS} = 3 mA	[7]	-	-	0.4	V
I_{LI}	input leakage current	$V_I = V_{DD}$	[13]	-	2	4	μA
		V_I = 5 V	[13]	-	10	22	μA
Oscillator pins							
$V_{i(XTAL1)}$	input voltage on pin XTAL1			−0.5	1.8	1.95	V
$V_{o(XTAL2)}$	output voltage on pin XTAL2			−0.5	1.8	1.95	V
$V_{i(RTCX1)}$	input voltage on pin RTCX1			−0.5	1.8	1.95	V
$V_{o(RTCX2)}$	output voltage on pin RTCX2			−0.5	1.8	1.95	V

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] The RTC typically fails when $V_{i(VBAT)}$ drops below 1.6 V.

[3] Including voltage on outputs in 3-state mode.

9.1 Timing

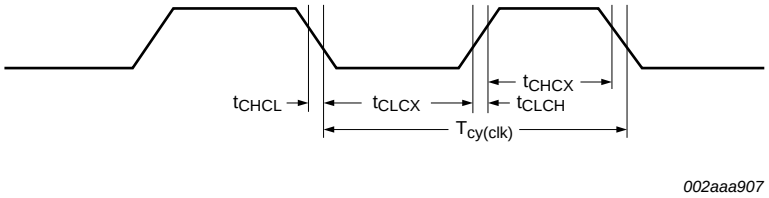
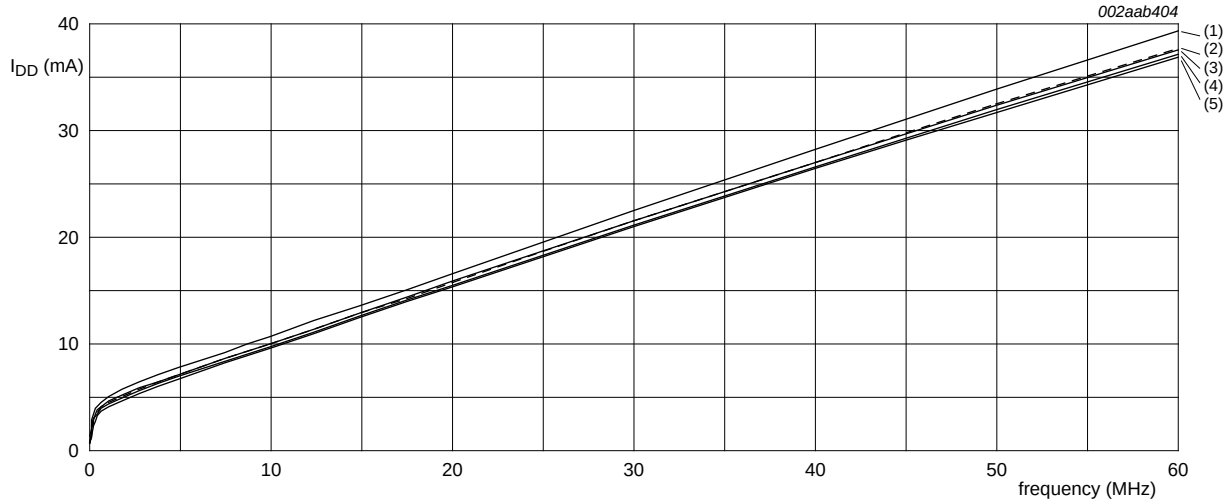


Fig 7. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

9.2 LPC2138 power consumption measurements



Test conditions: code executed from flash; all peripherals are enabled in PCONP register; PCLK = CCLK/4.

(1) V_{DD} = 3.6 V at −60 °C (max)

(2) V_{DD} = 3.6 V at 140 °C

(3) V_{DD} = 3.6 V at 25 °C

(4) V_{DD} = 3.3 V at 25 °C (typical)

(5) V_{DD} = 3.3 V at 95 °C (typical)

Fig 8. $I_{DD(act)}$ measured at different frequencies (CCLK) and temperatures

10. ADC electrical characteristics

Table 8. ADC static characteristics

V_{DDA} = 2.5 V to 3.6 V; T_{amb} = –40 °C to +85 °C unless otherwise specified; ADC frequency 4.5 MHz.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	V_{DDA}	V
C_{ia}	analog input capacitance			-	-	1	pF
E_D	differential linearity error		[1][2][3]	-	-	±1	LSB
$E_{L(adj)}$	integral non-linearity		[1][4]	-	-	±2	LSB
E_O	offset error		[1][5]	-	-	±3	LSB
E_G	gain error		[1][6]	-	-	±0.5	%
E_T	absolute error		[1][7]	-	-	±4	LSB
R_{vsi}	voltage source interface resistance		[8]	-	-	40	kΩ

[1] Conditions: V_{SSA} = 0 V, V_{DDA} = 3.3 V.

[2] The ADC is monotonic, there are no missing codes.

[3] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 11.

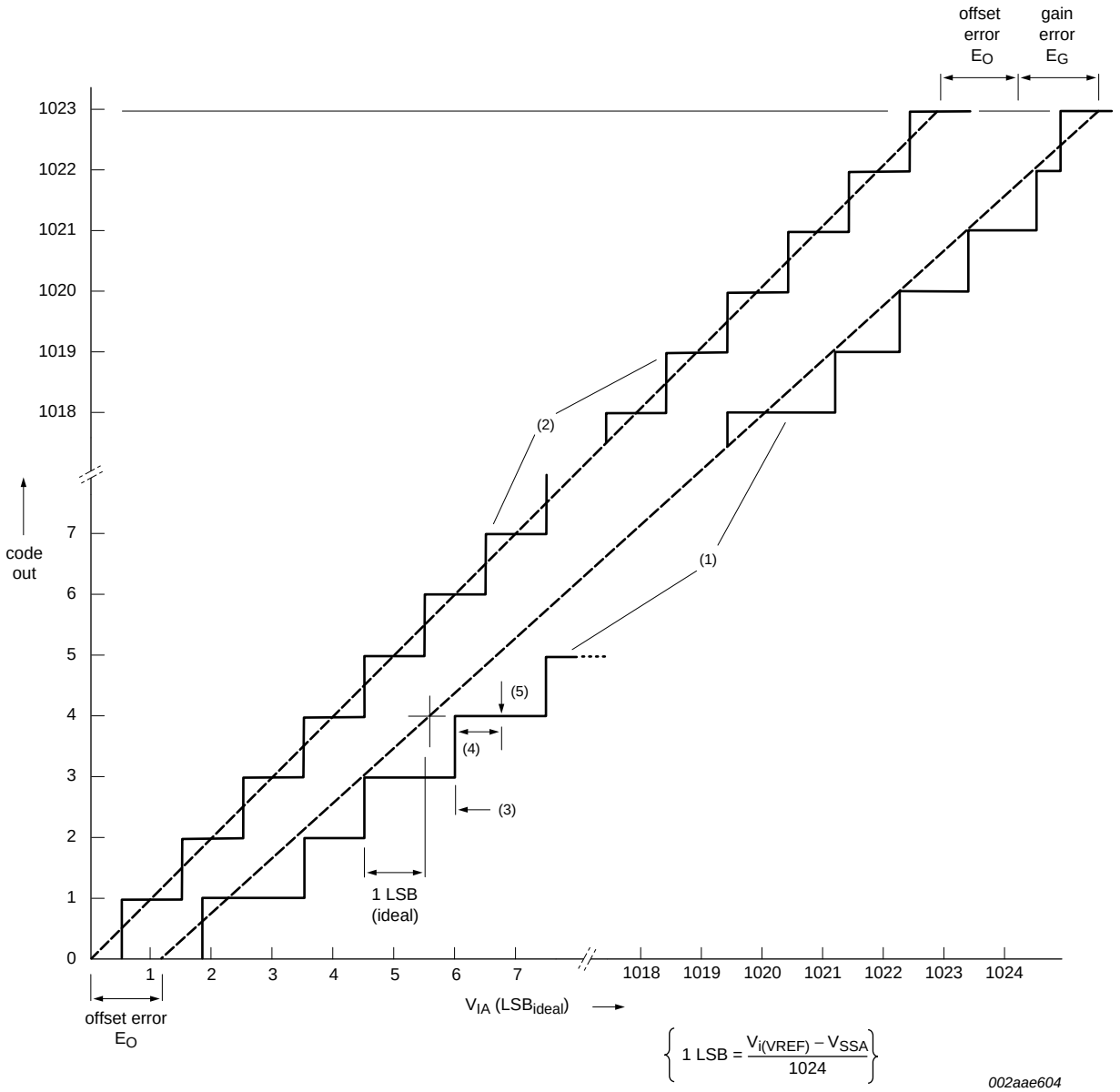
[4] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 11.

[5] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 11.

[6] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 11.

[7] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 11.

[8] See Figure 11.



(1) Example of an actual transfer curve.

(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

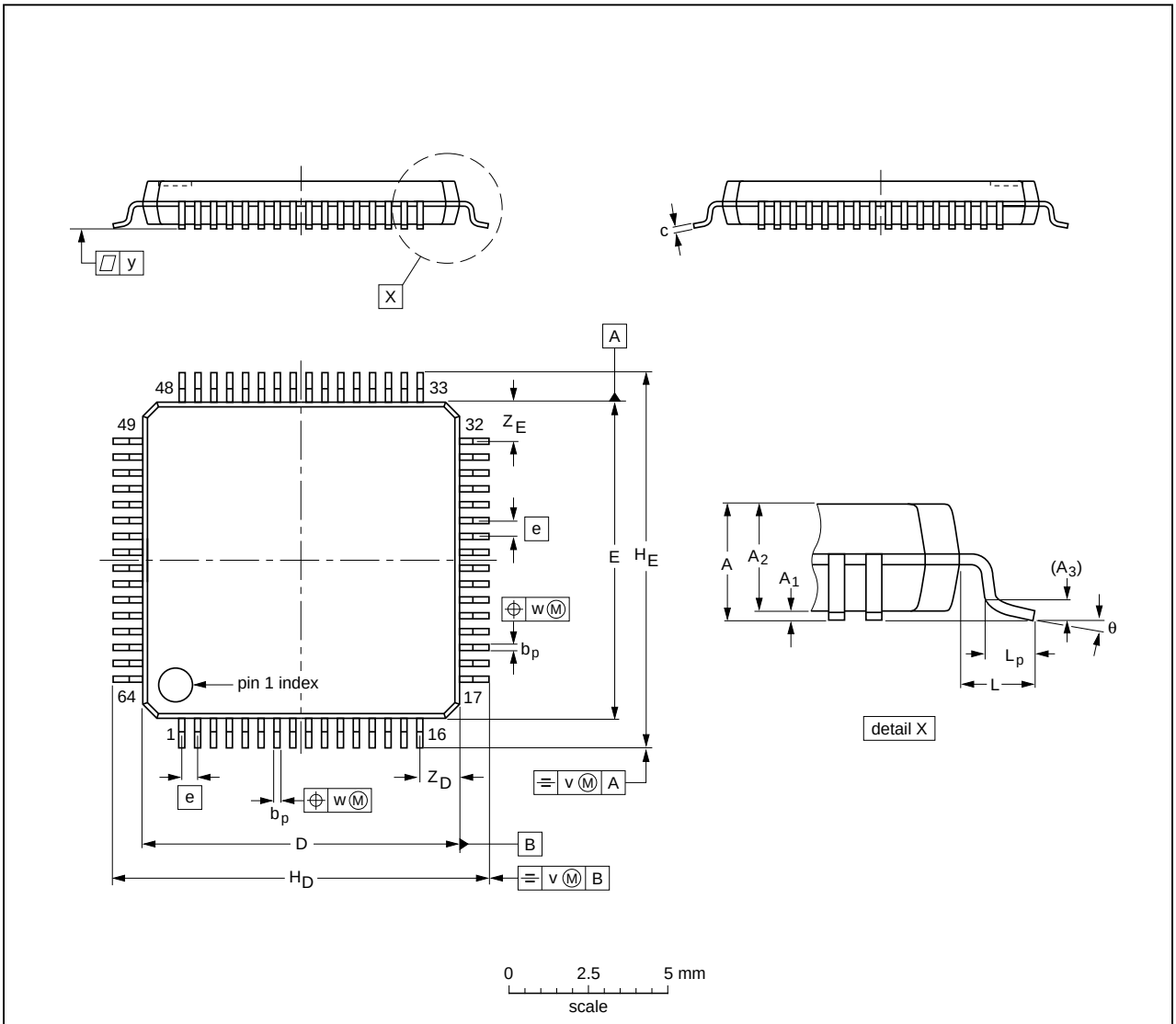
(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 11. ADC characteristics

13. Package outline

LQFP64: plastic low profile quad flat package; 64 leads; body 10 x 10 x 1.4 mm **SOT314-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.20 0.05	1.45 1.35	0.25	0.27 0.17	0.18 0.12	10.1 9.9	10.1 9.9	0.5	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.12	0.1	1.45 1.05	1.45 1.05	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT314-2	136E10	MS-026				~~00-01-19~~ 03-02-25

Fig 16. Package outline SOT314-2 (LQFP64)

15. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC2131_32_34_36_38 v.5.1	20110729	Product data sheet	-	LPC2131_32_34_36_38 v.5
Modifications:	• Parameter I_{sink} added in Table 5 “Limiting values”. • Table 6 “Static characteristics”: Updated crystal oscillator specs			
LPC2131_32_34_36_38 v.5	20110202	Product data sheet	-	LPC2131_32_34_36_38 v.4
Modifications:	• Table 3 “Pin description”: Added Table note [9] to RTCX1 and RTCX2 pins. • Table 6 “Static characteristics”, I^2C-bus pins: Changed typical hysteresis voltage from $0.5V_{DD}$ to $0.05V_{DD}$. • Table 6 “Static characteristics”: Removed table note for V_{IH} and V_{IL}. • Changed all occurrences of VPB to APB. • Table 6 “Static characteristics”: Added Table note [6] to V_I. • Table 6 “Static characteristics”, Standard port pins, $\overline{\text{RESET}}$, RTCK: V_{hys} hysteresis voltage (0.4 V) moved from typical to minimum. • Table 6 “Static characteristics”: Changed $V_{i(VREF)}$ minimum voltage from 3.0 V to 2.5 V. • Table 6 “Static characteristics”: Updated min, typical and max values for oscillator pins $V_{i(XTAL1)}$, $V_{o(XTAL2)}$, $V_{i(RTCX1)}$, and $V_{o(RTCX2)}$. • Added Section 11 “DAC electrical characteristics”. • Added Section 12 “Application information”.			
LPC2131_32_34_36_38 v.4	20071016	Product data sheet	-	LPC2131_32_34_36_38 v.3
LPC2131_32_34_36_38 v.3	20060921	Product data sheet	-	LPC2131_32_34_36_38 v.2
LPC2131_32_34_36_38 v.2	20050318	Preliminary data sheet	-	LPC2131_2132_2138 v.1
LPC2131_2132_2138 v.1	20041118	Preliminary data sheet	-	-

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17. Contact information

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18. Contents

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